☐ MN101C12D, MN101C12F, MN101C12G

Туре	MN101C12D , MN101C12F , MN101C12G			
ROM (×8-Bit)	64 K / 96 K / 128 K (External memory can be expanded)			
RAM (×8-Bit)	2 048 / 4 096 / 4 096 (External memory can be expanded)			
Minimum Instruction Execution Time	Standard: 0.10 μs (at 4.5 V to 5.5 V, 20 MHz) 0.25 μs (at 2.7 V to 5.5 V, 8 MHz) 125 μs (at 2.0 V to 5.5 V, 32 kHz)* Double speed: 0.12 μs (at 4.5 V to 5.5 V, 8.38 MHz) 0.25 μs (at 3.0 V to 5.5 V, 4 MHz) 62.5 μs (at 2.0 V to 5.5 V, 32 kHz)* * The lower limit for operation guarantee for EPROM built-in version is 2.7 V.			
Interrupts	• RESET • Watchdog • External 0 • External 1 • External 2 • External 3 • External 4 • Timer 0 • Timer 1 • Timer 2 • Timer 3 • Timer 4 • Timer 6 • Time Base • Serial 3 • Serial 1 • Serial 2 • Automatic Transfer finish • A/D Conversion finish • External 5 • Timer 7 (2 systems) • Key Interrupts (8 lines)			
Timer Counter	Timer Counter 0 : 8-Bit × 1 (Square-Wave/8-Bit PWM Output, Event Count, Generation of Remote Control Carrier, Pulse Width Measurement) Clock Source 1/2, 1/4 of System Clock, 1/1, 1/4, 1/16, 1/32, 1/64 of OSC Oscillation Clock, 1/1 of XI Oscillation Clock, External Clock Input Coincidence with Compare Register 0			
	Timer Counter 1 : 8-Bit × 1 (Square-Wave Output, Event Count, Synchronous Output Event) Clock Source 1/2, 1/8 of System Clock, 1/1, 1/4, 1/16, 1/64, 1/128 of OSC Oscillation Clock, 1/1 of XI Oscillation Clock, External Clock Input Coincidence with Compare Register 1			
	Timer Counter 0, 1 can be cascade-connected.			
	Timer Counter 2: 8-Bit × 1 (Square-Wave/8-Bit PWM Output, Event Count, Synchronous Output Event, Pulse Width Measurement) Clock Source 1/2, 1/4 of System Clock, 1/1, 1/4, 1/16, 1/32, 1/64 of OSC Oscillation Clock, 1/1 of XI Oscillation Clock, External Clock Input Coincidence with Compare Register 2			
	Timer Counter 3 : 8-Bit × 1 (Square-Wave Output, Event Count, Generation of Remote Control Carrier) Clock Source 1/2, 1/8 of System Clock, 1/1, 1/4, 1/16, 1/64, 1/128 of OSC Oscillation Clock, 1/1 of XI Oscillation Clock, External Clock Input Interrupt Source Coincidence with Compare Register 3			
	Timer Counter 2, 3 can be cascade-connected.			
	Timer Counter 4:8-Bit × 1 (Square-Wave/8-Bit PWM Output, Event Count, Pulse Width Measurement, Serial 1 Baud Rate Timer) Clock Source 1/2, 1/4 of System Clock, 1/1, 1/4, 1/16, 1/32, 1/64 of OSC Oscillation Clock, 1/1 of XI Oscillation Clock, 1/1 of External Clock Input Interrupt Source Coincidence with Compare Register 4			
	Timer Counter 6 : 8-Bit Freerun Timer			
	Clock Source 1/1 of System Clock, 1/1, 1/4096, 1/8192 of OSC Oscillation Clock, 1/1, 1/4096, 1/8192 of XI Oscillation Clock Interrupt Source . Coincidence with Compare Register 6			

Timer Counter (Continue)

Serial Interface

Timer Counter 7:16-Bit × 1 (Square-Wave/16-Bit PWM Output, Cycle / Duty continuous variable, Event Count,

Synchronous Output Evevt, Pulse Width Measurement, Input Capture)

Clock Source

1/1, 1/2, 1/4, 1/16 of System Clock, 1/1, 1/2, 1/4, 1/16 of OSC Oscillation

Clock, 1/1, 1/2, 1/4, 1/16 of External Clock Input

Coincidence with Compare Register 7 (2 lines) Interrupt Source

Time Base Timer (One-Minute Count Setting)

Clock Source 1/1 of OSC Oscillation Clock,

1/1 of XI Oscillation Clock

Interrupt Source 1/128, 1/256, 1/512, 1/1024, 1/8192, 1/32768, of Clock Source

Watchdog Timer

1/65536, 1/262144, 1/1048576 of System Clock Interrupt Source

DMA Controller (Automatic data transfer)

Max Transfer Cycles

Starting Factor External Request, Various Types of Interrupt, Software 1-Byte Transfer, Word Transfer, Burst Transfer

Transfer Mode

Serial 1: 8-Bit × 1 (Synchronous Type/Simple UART[Half-Duplex])

1/2, 1/4 of System Clock Clock Source

Pulse Output of Timer Counter 4

1/2, 1/4, 1/16, 1/64 of OSC Oscillation Clock

Serial 2:8-Bit × 1 (Synchronous Type)

Clock Source 1/2, 1/4 of System Clock

Pulse Output of Timer Counter 3

1/2, 1/4, 1/16, 1/32 of OSC Oscillation Clock

Serial 3: 8-Bit × 1 (Synchronous Type/Simple I²C)

Clock Source 1/2, 1/4 of System Clock

Pulse Output of Timer Counter 3

1/2, 1/4, 1/16, 1/32 of OSC Oscillation Clock

■ I/O Pins	1/0	73	• Common use • Specified pull-up Resistor available • Input / Output selectable (bit unit)		
	Input	15	Ommon use Specified pull-up Resistor available		
A/D Inputs			10-Bit × 8ch (with S/H)		
D/A Input	is	- N	8-Bit × 4ch		
Special Ports			Buzzer Output, Remote Control Carrier Signal Output, High-Current Drive Port		
Package	Package QFP100-P-1818B		QFP100-P-1818B		

Electrical Characteristics

Supply Current

Parameter	Symbol	Condition	Lim#		Hell
Cetassicio	49****	9999999	min typ	388X	•
	IDD1	fosc = 20 MHz, VDD = 5 V		60	mA
Operating Supply Current	IDD2	fosc = 8 39 MHz, VDD = 5 V		25	mA
	IDD3	fx = 32 768 kHz, VDD = 3 V		100	μА
Supply Current at HALT	IDD4	fx = 32 kHz, VDD = 3 V		8	μΑ
	IDD5	fx = 32 768 kHz, VDD = 3 V, Ta = -40 °C to +85 °C		20	μА
Supply Current at STOR	IDD6	VDD = 5 V, Ta = 25 °C		1	μΑ
Supply Current at STOP	IDD7	VDD = 5 V, Ta = -40 °C to +85 °C		30	μA

See the next page for support tool and pin assignment.

Support Tool

In-Circuit Emulator	PX-ICE101C / D + PX-PRB101C12-C / D		
EPROM built-in Type	Туре	MN101CP12GAF	
	ROM (× 8-Bit)	128 K	
	RAM (× 8-Bit)	4 096	
	Minimum Instruction Execution Time	Standard 0 10 μs (at 4 5 V to 5 5 V, 20 MHz) 0 25 μs (at 2 7 V to 5 5 V, 8 MHz)	
		Double speed 0 12 μs (at 4 5 V to 5 5 V, 8 38 MHz) 0 25 μs (at 3 0 V to 5 5 V, 4 MHz)	
	Package	QFP100-P-1818B	

Pin Assignment



QFP100-P-1818B

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